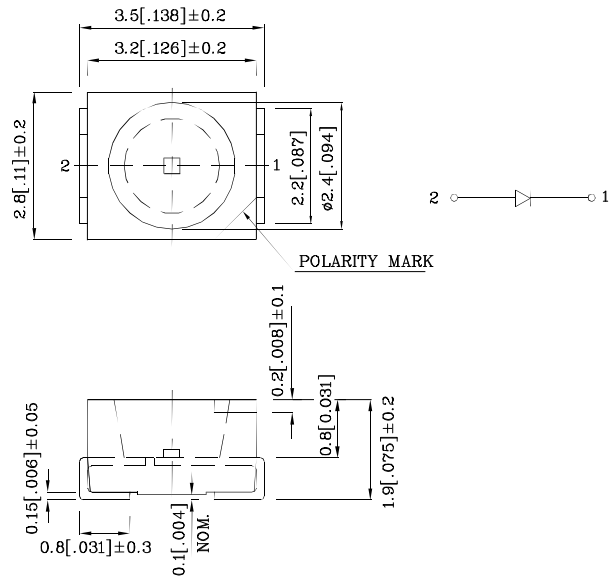


### Features

- Single color.
- Suitable for all SMT assembly and solder process.
- Available on tape and reel.
- Ideal for backlighting.
- Package : 1500pcs / reel.
- Moisture sensitivity level : level 3.
- Black case.
- RoHS compliant.



**ATTENTION**  
OBSERVE PRECAUTIONS  
FOR HANDLING  
ELECTROSTATIC  
DISCHARGE  
SENSITIVE  
DEVICES



### Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.25(0.01")$  unless otherwise noted.
3. Specifications are subject to change without notice.

Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ )		CWD (InGaN)	Unit
Reverse Voltage	$V_R$	5	V
Forward Current	$I_F$	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	$i_{FS}$	150	mA
Power Dissipation	$P_D$	120	mW
Operating Temperature	$T_A$	-40 ~ +85	°C
Storage Temperature	$T_{stg}$	-40 ~ +85	

Operating Characteristics ( $T_A=25^\circ\text{C}$ )		CWD (InGaN)	Unit
Forward Voltage (Typ.) ( $I_F=20\text{mA}$ )	$V_F$	3.3	V
Forward Voltage (Max.) ( $I_F=20\text{mA}$ )	$V_F$	4.0	V
Reverse Current (Max.) ( $V_R=5\text{V}$ )	$I_R$	50	$\mu\text{A}$
Chromaticity Coordinates (Typ.)	x	0.31	
	y	0.31	
Capacitance (Typ.) ( $V_F=0\text{V}$ , $f=1\text{MHz}$ )	C	100	pF

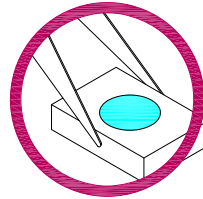
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity ( $I_F=20\text{mA}$ ) mcd		Viewing Angle 2 $\theta$ 1/2
				min.	typ.	
XZCWD45SB	White	InGaN	Water Clear	80	178	120°

## Handling Precautions

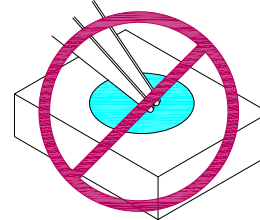
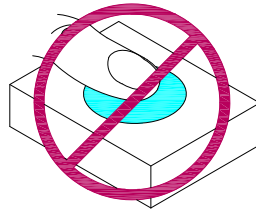
Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

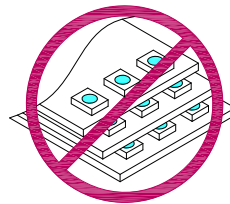
1. Handle the component along the side surfaces by using forceps or appropriate tools.



2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.



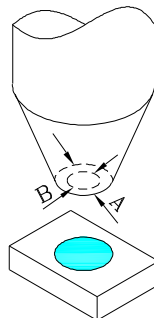
3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



4.1. The outer diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks. The inner diameter of the nozzle should be as large as possible.

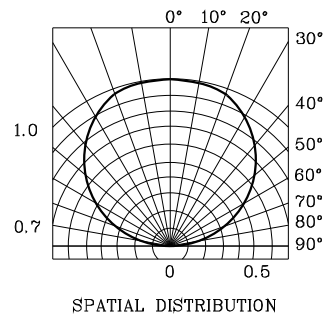
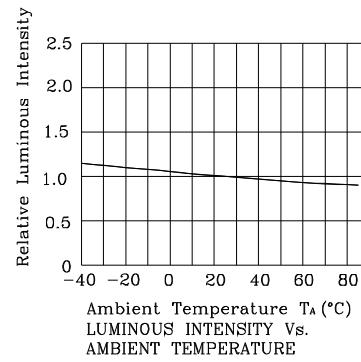
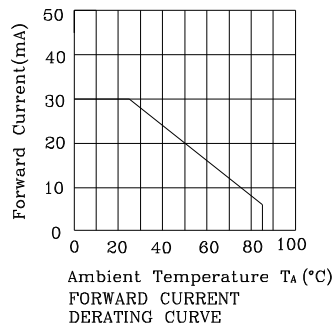
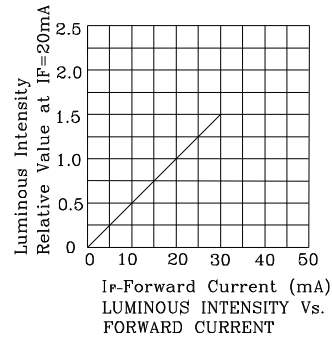
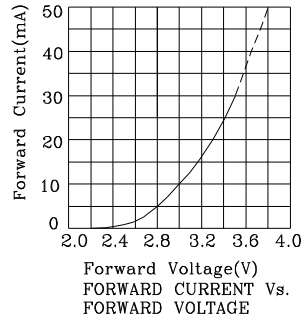
4.2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.

4.3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



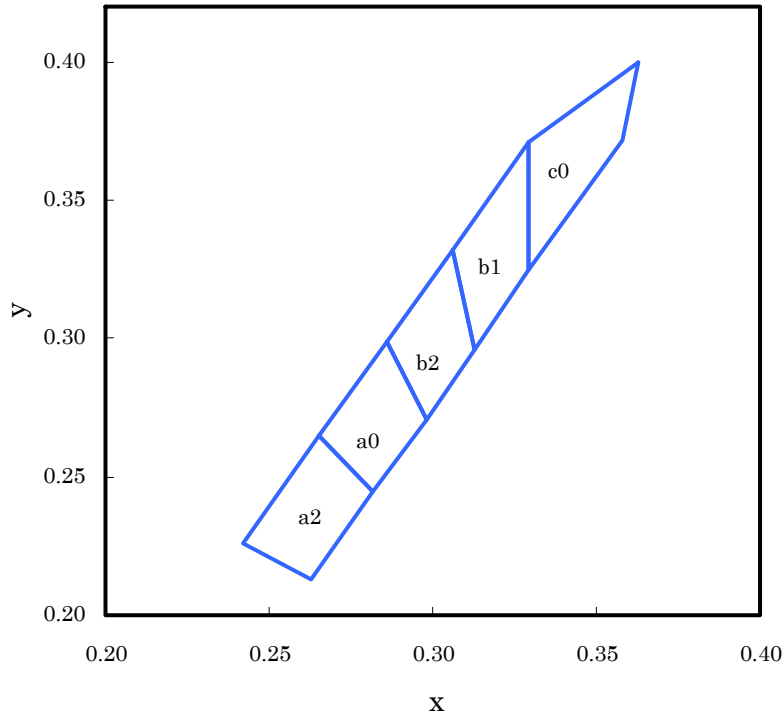
5. As silicone encapsulation is permeable to gases, some corrosive substances such as  $H_2S$  might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

❖ CWD



**XZCWD45SB**

**White CIE**

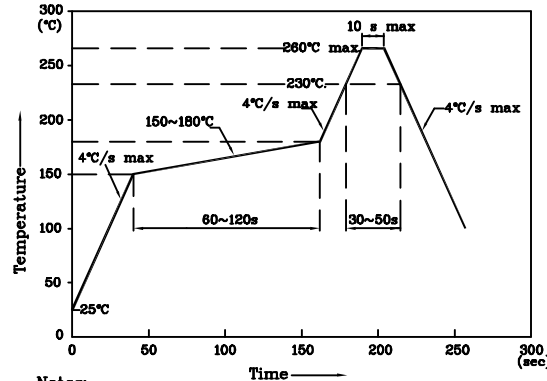


	x	y		x	y		x	y
a2	0.263	0.213	a0	0.282	0.245	b2	0.298	0.271
	0.282	0.245		0.298	0.271		0.313	0.296
	0.265	0.265		0.286	0.299		0.306	0.332
	0.242	0.226		0.265	0.265		0.286	0.299
b1	0.313	0.296	c0	0.329	0.325			
	0.329	0.325		0.358	0.372			
	0.329	0.371		0.363	0.400			
	0.306	0.332		0.329	0.371			

Notes:  
 Shipment may contain more than one chromaticity regions.  
 Orders for single chromaticity region are generally not accepted.  
 Measurement tolerance of the chromaticity coordinates is  $\pm 0.01$ .

Reflow soldering is recommended and the soldering profile is shown below.  
Other soldering methods are not recommended as they might cause damage to the product.

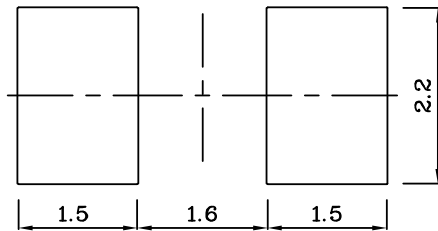
Reflow Soldering Profile for SMD Products (Pb-Free Components)



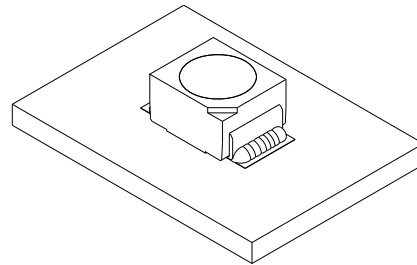
Notes:

1. Maximum soldering temperature should not exceed 260°C
2. Recommended reflow temperature: 145°C-280°C
3. Do not put stress to the epoxy resin during high temperatures conditions

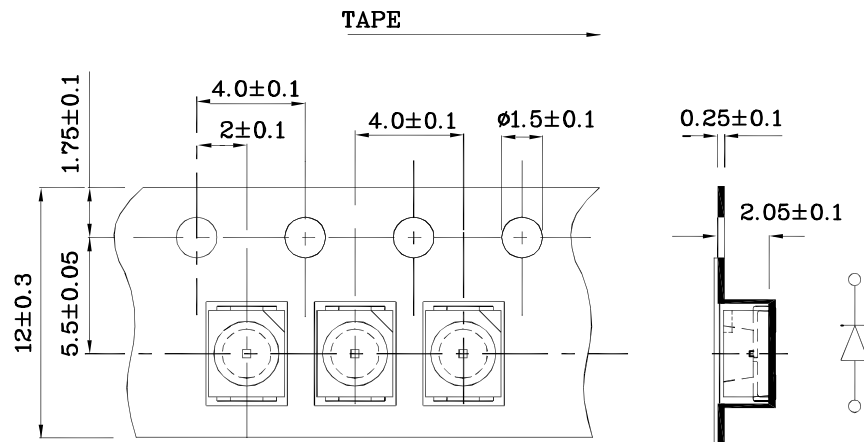
❖ Recommended Soldering Pattern  
(Units : mm; Tolerance: ±0.1)



❖ The device has a single mounting surface. The device must be mounted according to the specifications.



❖ Tape Specification (Units : mm)



Remarks:

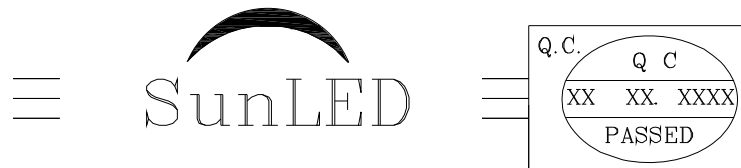
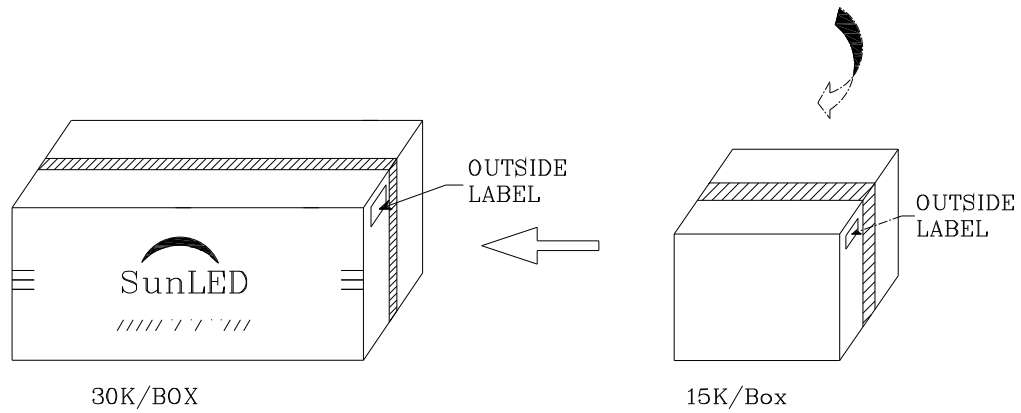
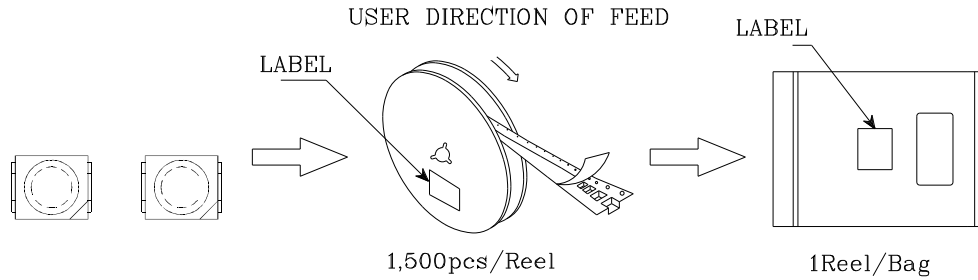
If special sorting is required (e.g. binning based on forward voltage, luminous intensity/ luminous flux or chromaticity), the typical accuracy of the sorting process is as follows:


1. Measurement tolerance of the chromaticity coordinates is ±0.01.
2. Luminous Intensity/ Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

**PACKING & LABEL SPECIFICATIONS**

**XZCWD45SB**



P/NO : XZxx45x	
QTY : 1,500 pcs	CODE: XXX
S/N : XX	
LOT NO:	
 XXXXXXXXXXXXXXXXXXXX	
RoHS Compliant	